

Nadine Gergel-Hackett

List of Publications by Year in descending order

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14
papers

467
citations

1040056

9
h-index

1058476

14
g-index

14
all docs

14
docs citations

14
times ranked

725
citing authors

#	ARTICLE	IF	CITATIONS
1	A Flexible Solution-Processed Memristor. IEEE Electron Device Letters, 2009, 30, 706-708.	3.9	210
2	Formation of Silicon-Based Molecular Electronic Structures Using Flip-Chip Lamination. Journal of the American Chemical Society, 2009, 131, 12451-12457.	13.7	48
3	Origin of Differing Reactivities of Aliphatic Chains on H ⁺ Si(111) and Oxide Surfaces with Metal. Journal of Physical Chemistry C, 2007, 111, 9384-9392.	3.1	34
4	Memristors With Flexible Electronic Applications. Proceedings of the IEEE, 2012, 100, 1971-1978.	21.3	33
5	Probing Molecules in Integrated Silicon-Molecule-Metal Junctions by Inelastic Tunneling Spectroscopy. Nano Letters, 2008, 8, 478-484.	9.1	31
6	Demonstration of Molecular Assembly on Si (100) for CMOS-Compatible Molecule-Based Electronic Devices. Journal of the American Chemical Society, 2008, 130, 4259-4261.	13.7	29
7	Molecule-induced interface states dominate charge transport in Si-alkyl-metal junctions. Journal of Physics Condensed Matter, 2008, 20, 374114.	1.8	26
8	Imaging of nanoscale charge transport in bulk heterojunction solar cells. Journal of Applied Physics, 2011, 109, 124501.	2.5	17
9	Fabrication and Characterization of Interconnected Nanowell Molecular Electronic Devices in Crossbar Architecture. IEEE Nanotechnology Magazine, 2009, 8, 574-581.	2.0	10
10	Engineering the Electron Transport of Silicon-Based Molecular Electronic Devices via Molecular Dipoles. Journal of Physical Chemistry C, 2010, 114, 21708-21714.	3.1	9
11	Structural and Electrical Properties of Flip Chip Laminated Metal-Molecule-Silicon Structures Varying Molecular Backbone and Atomic Tether. Journal of Physical Chemistry C, 2011, 115, 24353-24365.	3.1	8
12	Flexible Memristors Fabricated through Sol-Gel Hydrolysis. ECS Transactions, 2011, 35, 111-120.	0.5	6
13	(Invited) Three-Dimensionally Structured Thin Film Heterojunction Photovoltaics on Interdigitated Back-Contacts. ECS Transactions, 2010, 28, 521-532.	0.5	4
14	SPICE Behavioral Modeling of TiO ₂ Memristors for Digital Logic Applications. Journal of Circuits, Systems and Computers, 2021, 30, 2120002.	1.5	2